

Title (en)  
ETCHING SOLUTION

Title (de)  
ÄTZLÖSUNG

Title (fr)  
SOLUTION D'ATTAQUE

Publication  
**EP 0536362 B1 19960703 (DE)**

Application  
**EP 92908839 A 19920421**

Priority  
• DE 9200321 W 19920421  
• DE 4113283 A 19910424

Abstract (en)  
[origin: WO9219792A1] An etching solution for removing a metallic layer from a substrate contains a hydrogenated compound that dissolves the metal itself while evolving hydrogen and a nitro-substituted organic compound. The solution is characterized by the fact that the selected nitro-substituted organic compound is a compound having an easily hydrogenizable nitro group.

IPC 1-7  
**C23F 1/44**

IPC 8 full level  
**C23F 1/10** (2006.01); **C23F 1/20** (2006.01); **C23F 1/26** (2006.01); **C23F 1/28** (2006.01); **C23F 1/36** (2006.01); **C23F 1/44** (2006.01)

CPC (source: EP US)  
**C23F 1/10** (2013.01 - EP US); **C23F 1/20** (2013.01 - EP US); **C23F 1/26** (2013.01 - EP US); **C23F 1/28** (2013.01 - EP US);  
**C23F 1/36** (2013.01 - EP US); **C23F 1/44** (2013.01 - EP US)

Citation (examination)  
METAL FINISHING Bd. 89, Nr. 1A, Januar 1991, Seiten 388-396; STANLEY HIRSCH: 'stripping metallic coatings' siehe Seite 392-Seite 394

Designated contracting state (EPC)  
AT BE CH DE FR LI NL

DOCDB simple family (publication)  
**WO 9219792 A1 19921112**; AT E140041 T1 19960715; DE 4113283 A1 19921029; DE 4113283 C2 19940505; DE 59206696 D1 19960808;  
EP 0536362 A1 19930414; EP 0536362 B1 19960703; JP H06500363 A 19940113; US 5462640 A 19951031

DOCDB simple family (application)  
**DE 9200321 W 19920421**; AT 92908839 T 19920421; DE 4113283 A 19910424; DE 59206696 T 19920421; EP 92908839 A 19920421;  
JP 50795692 A 19920421; US 96280192 A 19921222